



(0.80 mm) .0315"

QTE SERIES

HIGH SPEED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/QTE

Insulator Material:
Liquid Crystal Polymer

Terminal Material:
Phosphor Bronze

Plating: Au or Sn over
50µ" (1.27 µm) Ni

Current Rating:

Contact:

2 A per pin

(1 pin powered per row)

Ground Plane:

23 A per ground plane

(1 ground plane powered)

Operating Temp Range:

-55°C to +125°C

Voltage Rating:

225 VAC mated with QSE

& 5 mm Stack Height

Max Cycles: 100

RoHS Compliant: Yes

Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (020-060)

Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

Board Mates:

QSE

Cable Mates:

EQCD, EQDP, EQRF

(See Also Available note)



QTE/QSE 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9 GHz / 18 Gbps	9 GHz / 18 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps	14 GHz / 28 Gbps
Differential Pair Signaling	-DP	8.5 GHz / 17 Gbps	13.5 GHz / 27 Gbps

*Performance data includes effects of a non-optimized PCB.

**Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com/QTE or contact sig@samtec.com

Integral metal plane
for power or ground

Standard stack heights
from 5 mm to 25 mm

**Protocols
Supported**

100 GbE

XAUI

PCI Express®

SATA

MGT (Rocket I/O)

InfiniBand™

Download app notes at:

www.samtec.com/appnote

Contact SIG @ samtec.com

for questions on protocols

Finalinch®
CERTIFIED

28+
Gbps

QTE	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-020, -040, -060 (40 total pins per bank = -D) -014, -028, -042 (14 pairs per bank = -D-DP)	Specify LEAD STYLE from chart	-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails -L = 10µ" (0.25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails -C* = Electro-Polished Selective 50µ" (1.27 µm) min Au over 150µ" (3.81 µm) Ni on Signal Pins in contact area, 10µ" (0.25 µm) min Au over 50µ" (1.27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1.27 µm) min Ni on all solder tails	-D = Single-Ended -D-DP = Differential Pair (-01 only)	-K = (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad -TR = Tape & Reel Packaging (N/A -05 & -07 lead style) -L = Latching Option (N/A on -042 & -060 positions)	

QTE LEAD STYLE	A	HEIGHT WITH QSE*
-01	(4.27) .168	(5.00) .197
-02	(7.26) .286	(8.00) .315
-03	(10.27) .404	(11.00) .433
-04	(15.25) .600	(16.00) .630
-05	(18.26) .718	(19.00) .748
-07	(24.24) .954	(25.00) .984
-09	(13.26) .522	(14.00) .551

*Processing conditions will affect mated height.

Diagram Dimensions:

-D-DP = (No. of Positions per Row/14) x (20.00) .7875

-D = (No. of Positions per Row/20) x (20.00) .7875

(20.00) .7875

(5.97) .235

(7.11) .280

(0.80) .0315

(0.20) .008

A

(0.76) .030

(0.89) .035 DIA

(0.64) .025

Diagram Labels:

01

02

Diagram Notes:

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- 15 mm, 22 mm and 30 mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
 - 30µ" (0.76 µm) Gold (Specify -H plating for Data Rate cable mating applications.)
 - Edge Mount
 - 56 (-DP), 80, 100 positions per row
 - Guide Posts, Screw Down & Friction Lock
 - Retention Option
- Contact Samtec.

OTHER SOLUTIONS

- Board Spacing Standoffs. See SO Series